

### **Product Change Notification / JAON-16KKNA763**

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22-Dec-2022

# **Product Category:**

Switchtec

# **PCN Type:**

Manufacturing Change

# **Notification Subject:**

CCB 5176.001 Final Notice: Qualification of an additional substrate material for selected PM411xxx, PM410xxx, PM401xxx, PM400xxx, PM420xxx, and PM421xxx device families available in 1467L BBGA (40x40x4.03mm) package at STAK assembly site.

### **Affected CPNs:**

JAON-16KKNA763\_Affected\_CPN\_12222022.pdf JAON-16KKNA763\_Affected\_CPN\_12222022.csv

#### **Notification Text:**

**PCN Status:**Final Notification

PCN Type:Manufacturing Change

**Microchip Parts Affected:**Please open one of the files found in the Affected CPNs section. Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:** Qualification of an additional substrate material for selected PM411xxx, PM410xxx, PM401xxx, PM400xxx, PM420xxx, and PM421xxx device families available in 1467L BBGA (40x40x4.03mm) package at STAK assembly site.

#### **Pre and Post Change Summary:**

	Pre Change	Post Change					
Assembly Site	STATS CHIPPAC KOREA LTD. (STAK)	STATS CHIPPAC KOREA LTD. (STAK)	STATS CHIPPAC KOREA LTD. (STAK)				
Substrate Material	E700GR	E700GR	E705G				
SM Material	SR7300GR	SR7300GR	SR7300GRB				
Bump Material	Sn1.8Ag	Sn1.8Ag	Sn1.8Ag				
Die Attach Material	WF6317	WF6317	WF6317				
Underfill Material	UF8830S	UF8830S	UF8830S				

### Impacts to Data Sheet:None

# Change ImpactNone

**Reason for Change:**To improve productivity and on time delivery performance by qualifying an additional substrate material.

# **Change Implementation Status:**In Progress

Estimated First Ship Date: January 30, 2023 (date code: 2305)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

### **Time Table Summary:**

	October 2022			->	December 2022				January 2023							
Workweek	4	4	4	4	4		4	5	5	5	5	1	2	3	4	5
	1	2	3	4	5		9	0	1	2	3					
Initial PCN Issue				\ <sub>V</sub>												
Date				Х												
Qual Report										Х						
Availability										^						
Final PCN Issue										Х						
Date										^						
Estimated																Χ
Implementation																
Date																

Method to Identify Change:Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Report.

**Revision History:**October 27, 2022: Issued initial notification.

December 22, 2022: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on January 30, 2023.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

### Attachments:

PCN\_JAON-16KKNA763\_Qual\_Report.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

#### **Terms and Conditions:**

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our <u>PCN</u> home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the <u>PCN FAQ</u> section.

If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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#### Affected Catalog Part Numbers (CPN)

PM41100B-FEI

PM41084B-FEI

PM41068B-FEI

PM40100B-FEI

PM40084B-FEI

PM40068B-FEI

PM42068B-FEI

PM42084B-FEI

PM42100B-FEI

PM40068B1-FEI

PM40084B1-FEI

PM40100B1-FEI

PM41068B1-FEI

PM41084B1-FEI

PM41100B1-FEI

PM42068B1-FEI

PM42084B1-FEI

PM42100B1-FEI

Date: Wednesday, December 21, 2022